

ABSTRACT

HIGH DENSITY CONTACT ARRANGEMENT

5 The present disclosure relates to a contact arrangement. The contact arrangement comprises a plurality of contacts (706) formed along a line (702) in a staggered configuration. The staggered configuration arranges the contacts so as to be diagonally spaced from each other along the line such that the contacts have an effective spacing along the line that is smaller than the actual spacing of the contacts. In one embodiment,
10 the contact arrangement is used to construct an integrated circuit chip assembly (906) that comprises a substrate (400) having a die (406) that is provided with a plurality of signal lines (702) and power lines (700) formed on its surface (402), the signal lines each including a plurality of signal contacts (706) and signal contacts of at least one signal line are arranged in a staggered configuration so as to be diagonally spaced from each other
15 along the at least one signal line such that the signal contacts have an effective spacing along the at least one signal line that is smaller than the actual spacing of the signal contacts of the at least one signal line.

Figure 8